

Title (en)
METHOD FOR PRODUCING AN ELECTRICAL THROUGH-PLATING

Title (de)
VERFAHREN ZUR HERSTELLUNG EINER ELEKTRISCHEN DURCHKONTAKTIERUNG

Title (fr)
PROCÉDÉ POUR LA PRODUCTION D'UN TROU D'INTERCONNEXION ÉLECTRIQUE

Publication
EP 2668664 A1 20131204 (DE)

Application
EP 12709304 A 20120307

Priority

- DE 102011005978 A 20110323
- EP 2012053849 W 20120307

Abstract (en)
[origin: WO2012126725A1] The invention relates to an integrated circuit (1), comprising a substrate (10) having a first surface (11) and an opposing second surface (12), wherein a functionalized region (13) is formed at least on the first surface (11) and wherein at least one electrical through-plating (40) is provided as a through-hole (42) which is continuously filled with an electrically conductive material (44) and which runs from the first surface (11) to the second surface (12) through the substrate (10). In order to ensure that the through-plating (40) can be reliably produced and is provided in a space-saving manner, the through-hole (42) has at least one gradation (46) on which a transition occurs from a smaller hole cross-section (d1) on the side of the first surface (11) to a larger hole cross-section (d2) on the side of the second surface (12).

IPC 8 full level
H01L 23/48 (2006.01); **H01L 21/768** (2006.01); **H01L 25/065** (2006.01)

CPC (source: EP US)
H01L 21/76898 (2013.01 - EP US); **H01L 23/481** (2013.01 - EP US); **H01L 24/11** (2013.01 - EP US); **H01L 24/13** (2013.01 - EP US); **H01L 24/92** (2013.01 - EP US); **H01L 25/0657** (2013.01 - EP US); **H01L 24/81** (2013.01 - EP US); **H01L 24/82** (2013.01 - EP US); **H01L 24/83** (2013.01 - EP US); **H01L 2224/0401** (2013.01 - EP US); **H01L 2224/06181** (2013.01 - EP US); **H01L 2224/10126** (2013.01 - EP US); **H01L 2224/11424** (2013.01 - EP US); **H01L 2224/13009** (2013.01 - EP US); **H01L 2224/13015** (2013.01 - EP US); **H01L 2224/131** (2013.01 - EP US); **H01L 2224/14181** (2013.01 - EP US); **H01L 2224/81801** (2013.01 - EP US); **H01L 2224/82101** (2013.01 - EP US); **H01L 2224/83** (2013.01 - EP US); **H01L 2224/9202** (2013.01 - EP US); **H01L 2224/92244** (2013.01 - EP US); **H01L 2225/06513** (2013.01 - EP US); **H01L 2225/06517** (2013.01 - EP US); **H01L 2225/06541** (2013.01 - EP US); **H01L 2924/01004** (2013.01 - EP US); **H01L 2924/01005** (2013.01 - EP US); **H01L 2924/01032** (2013.01 - EP US); **H01L 2924/01052** (2013.01 - EP US); **H01L 2924/01057** (2013.01 - EP US); **H01L 2924/01075** (2013.01 - EP US); **H01L 2924/01079** (2013.01 - EP US); **H01L 2924/014** (2013.01 - EP US); **H01L 2924/12042** (2013.01 - EP US); **H05K 3/3436** (2013.01 - EP US)

Citation (search report)
See references of WO 2012126725A1

Designated contracting state (EPC)
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)
DE 102011005978 A1 20120927; EP 2668664 A1 20131204; US 2014084428 A1 20140327; WO 2012126725 A1 20120927

DOCDB simple family (application)
DE 102011005978 A 20110323; EP 12709304 A 20120307; EP 2012053849 W 20120307; US 201214006913 A 20120307